



Plastic-Encapsulate MOSFETS

N-Channel 20-V(D-S) MOSFET

FEATURE

TrenchFET Power MOSFET

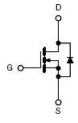
APPLICATIONS

- Load Switch for Portable Devices
- DC/DC Converter

SOT23

1. GATE
2. SOURCE
3. DRAIN

MARKING: A2SHB



Maximum ratings (T_a=25℃ unless otherwise noted)

Parameter	Symbol	Value	Unit	
Drain-Source Voltage	V _{DS}	20	- V	
Gate-Source Voltage	V _{GS}	±8		
Continuous Drain Current	I _D	2.8	Α	
Continuous Source-Drain Current(Diode Conduction)	ls	0.6	^	
Power Dissipation	P _D	0.35	W	
Thermal Resistance from Junction to Ambient (t≤5s)	R _{θJA}	357	°C/W	
Operating Junction	TJ	150	°C	
Storage Temperature	T _{STG}	-55 ~+150		





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Electrical characteristics (T_a=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Тур	Max	Units	
Static	•						
Drain-source breakdown voltage	V _{(BR)DSS}	V _G S = 0V, I _D =10μA	20			V	
Gate-threshold voltage	VGS(th)	V _{DS} =V _{GS} , I _D =50μA	0.65	0.95	1.2	V	
Gate-body leakage	I _{GSS}	V _{DS} =0V, V _{GS} =±8V			±100	nA	
Zero gate voltage drain current	I _{DSS}	V _{DS} =20V, V _{GS} =0V			1	μΑ	
Drain-source on-resistance ^a		V _{GS} =4.5V, I _D =3.6A		0.045	0.060		
	rDS(on)	Vgs =2.5V, ID =3.1A		0.070	0.115	Ω	
Forward transconductance ^a	G fs	V _{DS} =5V, I _D =3.6A		8		S	
Diode forward voltage	V _{SD}	I _S =0.94A,V _{GS} =0V		0.76	1.2	V	
Dynamic				•		•	
Total gate charge	Qg	V _{DS} =10V,V _{GS} =4.5V,I _D =3.6A		4.0	10	nC	
Gate-source charge	Q _{gs}			0.65			
Gate-drain charge	Q _{gd}			1.5			
Input capacitance ^b	C _{iss}	V _{DS} =10V,V _{GS} =0V,f=1MHz		300			
Output capacitance ^b	Coss			120		pF	
Reverse transfer capacitance ^b	C _{rss}			80			
Switching ^b	-1				'	'	
Turn-on delay time	t _{d(on)}			7	15		
Rise time	tr	V _{DD} =10V, R _L =5.5Ω, I _D ≈3.6A,		55	80	no	
Turn-off delay time	td(off)			16	60	ns	
Fall time	tf	V_{GEN} =4.5V,Rg=6 Ω		10	25		

Notes:

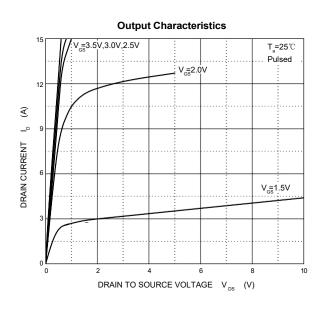
- a. Pulse Test : Pulse width≤300µs, duty cycle ≤2%.
- b. These parameters have no way to verify.

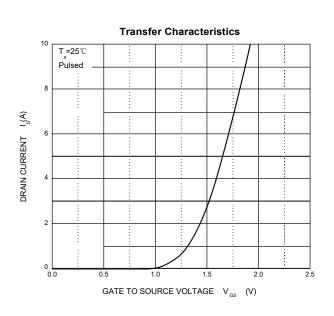


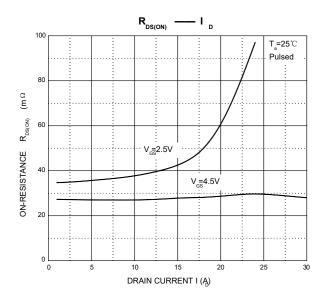


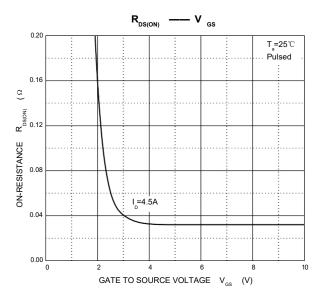
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Typical Characteristics









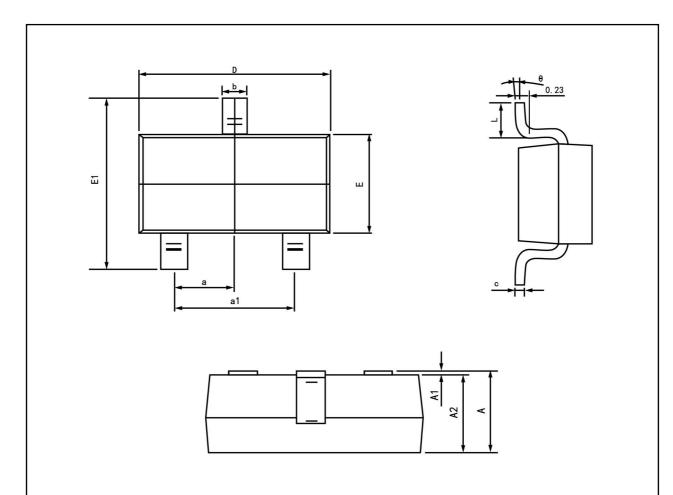
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SI2302 Plastic-Encapsulate MOSFETS

SOT-23-3L Package Outline Dimensions



Symbol	Dimension in Millimeters			
Зушьог	Min	Max		
A	1.050	1.250		
A1	0.000	0.100		
A2	1.050	1.150		
b	0.300	0.500		
С	0.100	0.200		
D	2.820	3.020		
E	1.500	1.700		
E1	2.650	2.950		
е	0.950 (Basic)			
e1	1.800	2.000		
L	0.300 0.600			
θ	0° 8°			



HF ROHS

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